

2. (Amended) The ESD protection circuit of claim 1, further comprising a lateral shunt resistor coupled between the cathode and the external triggering device.

4. (Amended) The ESD protection circuit of claim 3, wherein a surface area between the respective first and second high-doped regions of the first and second bipolar transistors are blocked from shallow trench isolation.

15. (Amended) An electrostatic discharge (ESD) protection circuit in a semiconductor integrated circuit (IC) having protected circuitry, the ESD protection circuit comprising:

a SCR further comprising:

a substrate;

a N-well and an adjacent P-well formed in said substrate and defining a junction therebetween;

at least one N+ doped region in said P-well and coupled to ground;

a P+ doped region in said N-well and coupled to a pad of said protected circuitry;

at least one P+ doped trigger tap disposed proximate to at least one N+ doped region in said P-well; and

an external on-chip triggering device coupled to the SCR, wherein one terminal is coupled to the pad and a second terminal is coupled to the trigger tap.

17. (Amended) The ESD protection circuit of claim 15, wherein a surface area between the at least one N+ doped region and the P+ doped region is shallow trench isolation blocked.

24. (Amended) An electrostatic discharge (ESD) protection circuit in a semiconductor integrated circuit (IC) having protected circuitry, the ESD protection circuit comprising:

a SCR further comprising: